

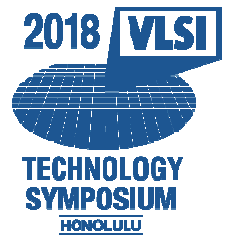


2018 Spintronics Workshop on LSI

June 17, 2018, 19:00 – 22:00

Hilton Hawaiian Village, Honolulu 2-3, Tapa Tower

Honolulu, Hawaii, USA



TOHOKU UNIVERSITY

General Information

The 2018 Spintronics Workshop on LSI will be held at Hilton Hawaiian Village, Honolulu, Hawaii, USA, on June 17, 2018, in conjunction with the VLSI Symposium on Technology as a Satellite Workshop of the 2018 VLSI Symposia. The workshop will focus on spintronics-based LSI technologies for high performance and ultra low power systems. Papers on current status, prospects and the remaining challenges in this field will be presented from invited speakers. The workshop is sponsored by Center for Innovative Integrated Electronic Systems (CIES), and Center for Spintronics Integrated Systems (CSIS), Tohoku University.

Registration

The workshop fee is free of charge, but registration is required.

http://www.cies.tohoku.ac.jp/2018_Spintronics_WS/

Deadline of advanced registration:

June 11th, 2018

Registration desk open at 6:30pm

Program

19:00-19:05	Opening remarks: Tetsuo Endoh (Tohoku University, Workshop Program Chair)
19:05-19:35	Invited talk 1 Jon Slaughter (IBM) Status, challenges, and recent developments in commercial MRAM technology
19:35-20:05	Invited talk 2 Danny Shum (GLOBALFOUNDRIES) Embedded MRAM for LLC applications: Materials Integration & Macro Design requirements
20:05-20:35	Invited talk 3 Hochul Lee (Qualcomm) Applications of spintronic devices in embedded security
20:35-21:05	Invited talk 4 Thomas Jew (NXP) Embedding MRAM into IOT and automotive applications
21:05-21:35	Invited talk 5 Hideo Sato (Tohoku Univ.) High-performance perpendicular-anisotropy (Co)FeB/MgO-based magnetic tunnel junctions and challenges for their scaling down to single-digit nanometer
21:35-21:45	Closing remarks: Tetsuo Endoh (Tohoku University, Workshop Program Chair)

Committee

Program Chair

Tetsuo Endoh (Tohoku Univ.)

Program Committee

H. S. Philip Wong (Stanford Univ., IEEE Executive Committee Chair of 2018 Symposia on VLSI Technology and Circuits)

Tadahiro Kuroda (Keio Univ., JSAP Executive Committee Chair of 2018 Symposia on VLSI Technology and Circuits)

Shoji Ikeda (Tohoku Univ.)

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